

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"5939775".pn. "20010034083".pn.	US-PGPUB; USPAT	OR	OFF	2010/11/08 12:16
L2	412	257/791.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2010/11/08 13:03
L3	10988	438/124.ccls. 438/126.ccls. 438/127.ccls. 257/787.ccls. 257/788.ccls. 257/791.ccls. 257/e23.12.ccls. 257/ e21.504.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2010/11/08 13:09
L4	443	L3 and ((siloxane polysiloxane organosiloxane organopolysiloxane silicone) same (inject\$6 mold\$6 cavity) same (heat \$6 curable curing cure cured liquid))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2010/11/08 13:09
L5	134	(CHENG-TAMMY DOBRZELEWSKI DOBRZELEWSKI-M DOBRZELEWSKI-MARK SOLOMON-DANIEL SOLOMON-DANIEL-M SOLOMON-DANIEL- STEVEN SOLOMON-D WINDIATE-C WINDIATE- CHRISTOPHER WINDIATE). in.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2010/11/08 13:22
L6	8	L5 and (siloxane polysiloxane organosiloxane organopolysiloxane silicone)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2010/11/08 13:22

L7	279	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) and (inject\$6 with (mold\$6 cavity)) and (heat \$6 curable curing cure cured) and (clamp\$6 force ton pressure speed mpa pascal megapascal)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/08 13:23
L8	395	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity)) same (heat\$6 curable curing cure cured) same (clamp\$6 force ton pressure speed mpa pascal megapascal)	US-PGPUB; USPAT	OR	ON	2010/11/08 13:35
L10	39	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity)) same (heat\$6 curable curing cure cured) same (addition near2 reaction)	US-PGPUB; USPAT	OR	ON	2010/11/08 13:58
L11	35	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity)) same (heat\$6 curable curing cure cured) same ((chip die component element ic integrated substrate dice) with (bond \$6 join\$6 attach\$6 mount \$6) with (siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition adhe\$8))	US-PGPUB; USPAT	OR	ON	2010/11/08 14:10

L12	71	((siloxane polysiloxane organosiloxane organopolysiloxane silicone) with (composition liquid encapsula\$6 resin epoxy)) same (inject\$6 with (mold\$6 cavity) with gate) same (heat\$6 curable curing cure cured)	US-PGPUB; USPAT	OR	ON	2010/11/08 14:11
L13	39	(composition liquid encapsula\$6 resin epoxy) same (inject\$6 with (mold \$6 cavity) with gate) same (heat\$6 curable curing cure cured) same (bond\$6 near wir\$6)	US-PGPUB; USPAT	OR	ON	2010/11/08 14:18

EAST Search History (I nterference)

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